



PS-0230

Product Description:

PS-0230 is a modified polyurethane adhesive which is initially applied with pressure and further activated with application of heat. PS-0230 can be used for bonding high and low surface energy substrates on a wide range of electronic products.

Construction / Properties:

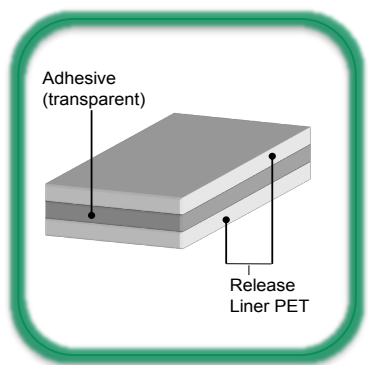
| Property | Value | Test Method |
|---------------------------------|------------------------------|-------------|
| Available Thickness | 0.1 mm | QSP-726 |
| Color | Colorless (Transparent) | -- |
| Adhesive Peel Strength | >1 Kgf (SUS 304 and PI Film) | QSP-722 |
| Shear Strength | >10 Kgf | -- |
| Bonding Conditions | 80 - 100 C | -- |
| Recommended Storage Temperature | 10 - 40 C | -- |

Test Method Summary

Substrates: 1mm thickness
 Bonding Area: 5mm x 5mm
 Bonding Conditions: 150 C/0.2 Mpa/10 sec
 Mechanical Bonding Method: Up and Down Plate Heating System
 Pre-fixing → Pressing/Bonding → 1 hr Aging at Room Temperature
 Bond Strength Determined using UTM Tester at 50mm/min

Features

- Converter Friendly
- Excellent Shear Strength
- Resistant to Moisture
- Prebonding is not necessary



Specific tests should be performed by the end user to determine the product suitability for the particular application.

For Additional Information:
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